

# RCJ331N25

## Nch 250V 33A Power MOSFET

V <sub>DSS</sub>	250V
R <sub>DS(on)</sub> (Max.)	105mΩ
l <sub>D</sub>	±33A
P <sub>D</sub>	211W

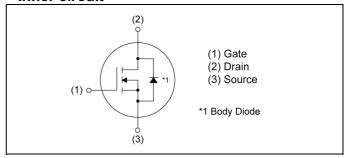
# Outline TO-263S



#### Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free plating; RoHS compliant
- 6) 100% Avalanche tested

## ●Inner circuit



Packaging specifications

<u> </u>	Jing specifications	
	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	24
	Quantity (pcs)	1000
	Taping code	TL
	Marking	RCJ331N25

## Application

Switching

## ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

	ч ,	· ,		
Parameter		Symbol	Value	Unit
Drain - Source voltage	$V_{DSS}$	250	V	
Continuous dusin summent	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	±33	Α
Continuous drain current	T <sub>c</sub> = 100°C	I <sub>D</sub> *1	17.9	Α
Pulsed drain current	I <sub>DP</sub> *2	132	Α	
Gate - Source voltage	$V_{GSS}$	±30	V	
Avalanche energy, single pulse		E <sub>AS</sub> *3	74.8	mJ
Avalanche current, repetitive		I <sub>AR</sub> *3	16.5	Α
$T_{c} = 25^{\circ}C$		P <sub>D</sub>	211	W
Power dissipation $T_a = 25^{\circ}C$		P <sub>D</sub> *4	1.56	W
Junction temperature		T <sub>j</sub>	150	°C
Operating junction and storage ter	mperature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Doromotor	Symbol	Values			Lleit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	0.59	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davameter	Cymah al	Symbol Conditions Min.		Values	Unit	
Parameter	Symbol			Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		250	-	-	V
		V <sub>DS</sub> = 250V, V <sub>GS</sub> = 0V				
Zero gate voltage drain current	I <sub>DSS</sub>	T <sub>j</sub> = 25°C	-	-	10	μA
didiri odriorit		T <sub>j</sub> = 125°C	-	-	-	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage V <sub>GS(th)</sub>		$V_{DS}$ = 10V, $I_D$ = 1mA	3.0	1	5.0	٧
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 16.5A	-	77	105	
Static drain - source on - state resistance	$R_{DS(on)}^{*5}$	V <sub>GS</sub> = 10V, I <sub>D</sub> = 16.5A	_	165	230	mΩ
		$T_j = 125^{\circ}C$				
Forward Transfer Admittance	Y <sub>fs</sub>  *5	V <sub>DS</sub> = 10V, I <sub>D</sub> = 16.5A	10	20	-	S

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $\simeq$  500 $\mu$ H, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 $\Omega$ , starting T<sub>j</sub> = 25 $^{\circ}$ C

<sup>\*4</sup> Mounted on a epoxy PCB FR4 (25mm×27mm×0.8mm)

<sup>\*5</sup> Pulsed

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Daramatar	Cymah al	Conditions		Values		Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	4500	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	220	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	130	-	
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DD} \simeq 125V$ , $V_{GS} = 10V$	-	50	1	
Rise time	<b>t</b> <sub>r</sub> *5	I <sub>D</sub> = 16.5A	-	200	-	20
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L \simeq 7.6\Omega$	-	120	-	ns
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	140	-	

## ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumb al	Conditions	Values			l leit	
Parameter	Symbol	ymbol Conditions -		Тур.	Max.	Unit	
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≃ 125V	-	80	-		
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 33A	-	25	-	nC	
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	-	27	-		
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 125V, I <sub>D</sub> = 33A	-	6.6	-	V	

## ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions		Values				
Farameter	Symbol	nbol Conditions		Symbol Conditions		Тур.	Max.	Unit
Continuous forward current	I <sub>S</sub> *1	T <sub>C</sub> = 25°C	-	1	26	Α		
Pulse forward current	I <sub>SP</sub> *2	1C - 25 C	-	1	104	Α		
Forward voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_{S} = 33A$	-	-	1.5	V		
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 16.5A	-	145	-	ns		
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/µs	-	670	-	nC		

Fig.1 Power Dissipation Derating Curve

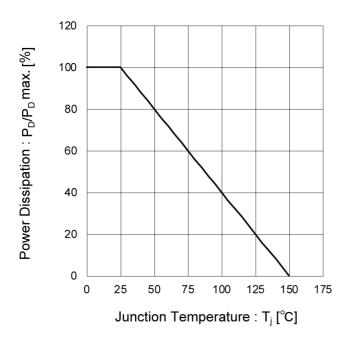


Fig.2 Maximum Safe Operating Area

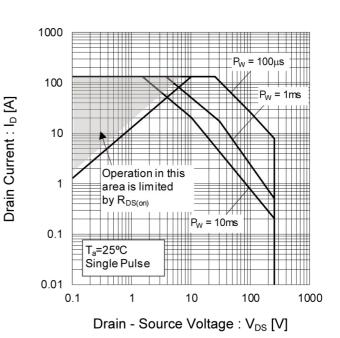
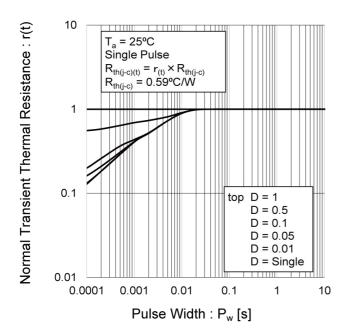


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



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Fig.4 Avalanche Current vs. Inductive Load

 $[V_{DD}=50V,R_{G}=25\Omega] \\ V_{GF}=10V,V_{GR}=0V \\ Starting T_{ch}=25^{\circ}C \\ \end{bmatrix}$ 

Fig.5 Avalanche Energy Derating Curve vs. Junction Temperature

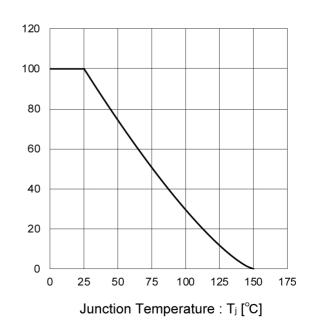
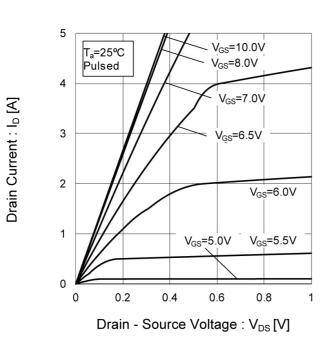


Fig.6 Typical Output Characteristics(I)



Drain Current : I<sub>D</sub> [A]

Avalanche Energy: E<sub>AS</sub> / E<sub>AS</sub> max [%]

30 T<sub>a</sub>=25℃ Pulsed V<sub>GS</sub>=10.0V 25 V<sub>GS</sub>=8.0V 20  $V_{GS}=7.0V$ 15 10 V<sub>GS</sub>=6.5V V<sub>GS</sub>=6.0V 5 V<sub>GS</sub>=5.5V 0 2 0 6 10

Fig.8 Typical Output Characteristics(II)

 $Drain - Source\ Voltage: V_{DS}[V]$ 

Fig.8 Breakdown Voltage vs. Junction Temperature

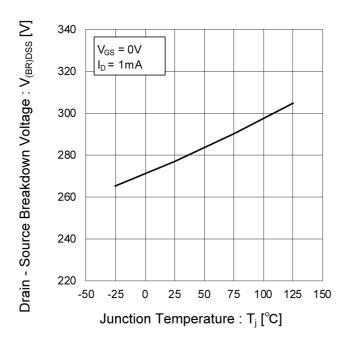


Fig.9 Typical Transfer Characteristics

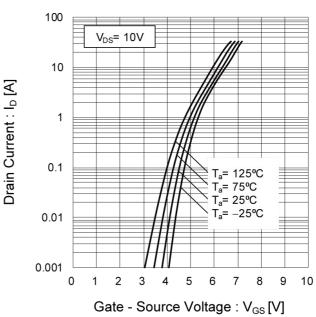


Fig.10 Gate Threshold Voltage vs. Junction Temperature

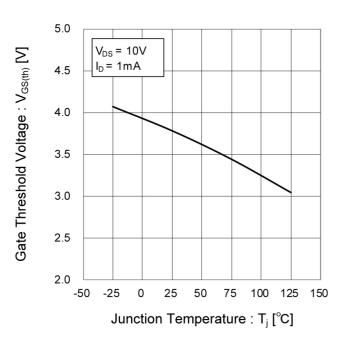
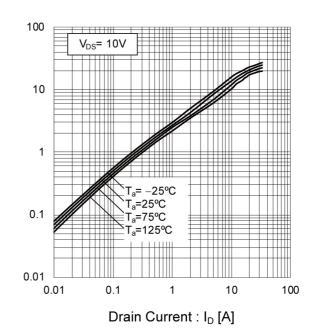


Fig.11 Transconductance vs. Drain Current



Transconductance : g<sub>fs</sub> [S]

RCJ331N25

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

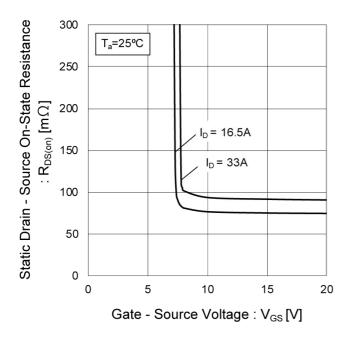


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

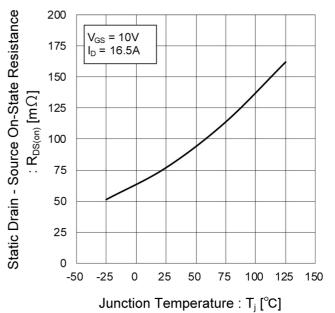




Fig.14 Static Drain - Source On - State Resistance vs. Drain Current

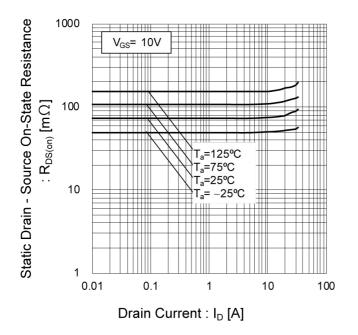


Fig.15 Drain Current Derating Curve

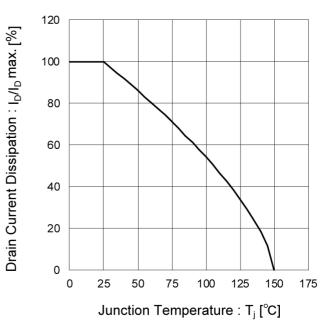




Fig.16 Typical Capacitance vs. Drain - Source Voltage

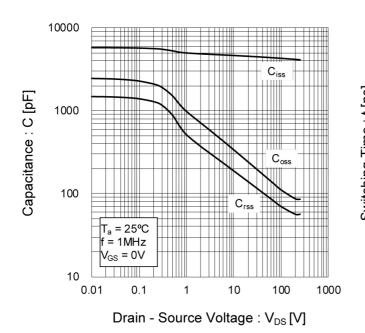


Fig.17 Switching Characteristics

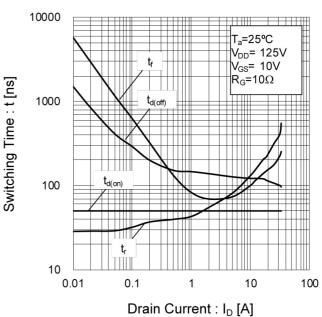
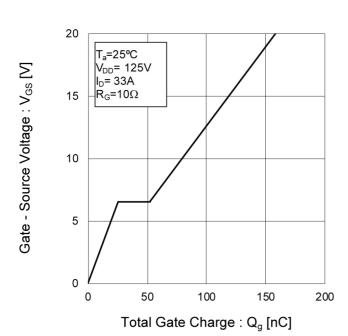


Fig.18 Dynamic Input Characteristics



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Fig.19 Source Current vs. Source-Drain Voltage

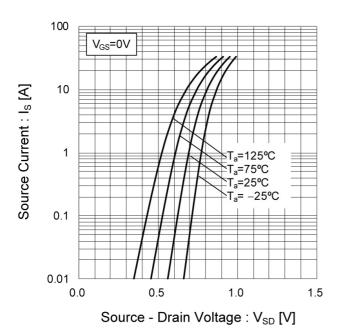
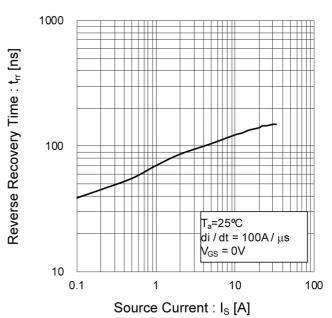


Fig.20 Reverse Recovery Time vs. Source Current





## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

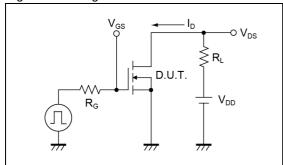


Fig.2-1 Gate Charge Measurement Circuit

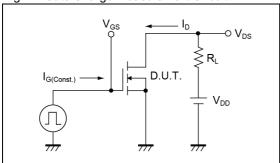


Fig.3-1 Avalanche Measurement Circuit

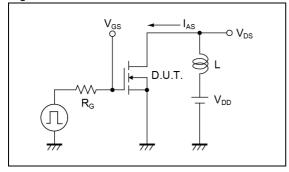


Fig.1-2 Switching Waveforms

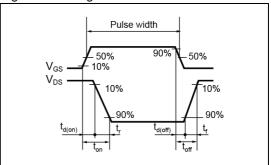


Fig.2-2 Gate Charge Waveform

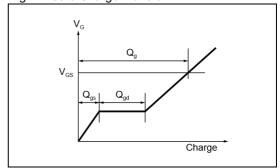
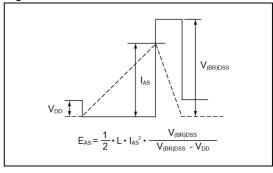
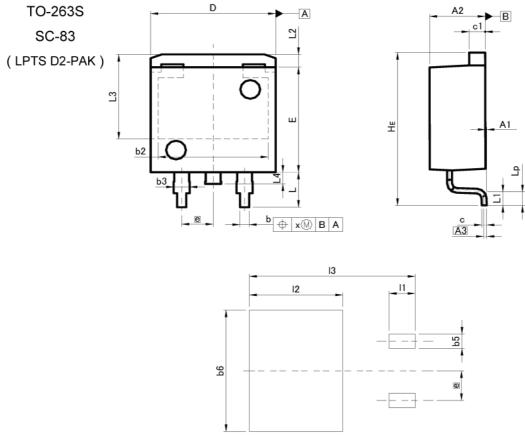


Fig.3-2 Avalanche Waveform



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.9	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
ט	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.1	00
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	1.3	20	0.0	47
L2	1.	10	0.0	43
L3	7.:	25	0.285	
L4	1.0	00	0.039	
Lp	0.90	1.50	0.035	0.059
Х		0.25	-	0.010
	N 471 73 41		T TNO	

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b5	1	1.23	-	0.049
b6	1	10.40	-	0.409
	3	2.10	1	0.083
12	-	7.55	-	0.297
13	-0	13.40	-	0.528

Dimension in mm/inches

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JÁPAN	USA	EU	CHINA
CLASSⅢ	О 400 Ш	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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